



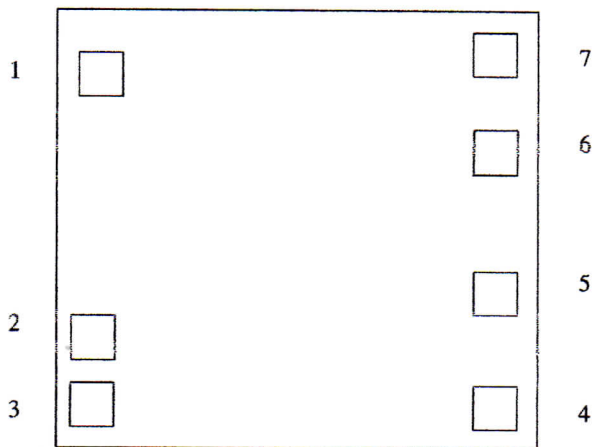
# Sierra Components, Inc.

2222 Park Place • Suite 3E • Minden, Nevada 89423  
 Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

### PAD FUNCTIONS

1. Inverting Input
2. Non-inverting Input
3. -Vs
4.  $V_L$
5. Output
6. +Vs
7.  $V_H$



**Top Material: Al**  
**Backside Material: Si Nitride**  
**Bond Pad Size: .004" X .004"**  
**Backside Potential: -Vs or Floating**  
**Mask Ref: M000948**

APPROVED BY: DK

DIE SIZE .037" X .038"

DATE: 2/7/13

MEG: TEXAS INSTRUMENTS

THICKNESS: 025"Max

P/N: OPA600